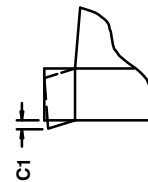
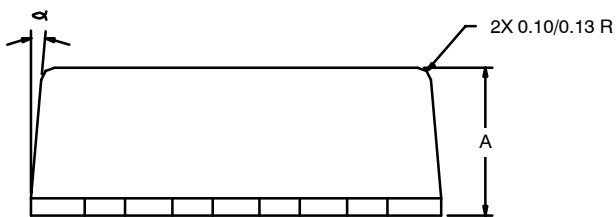
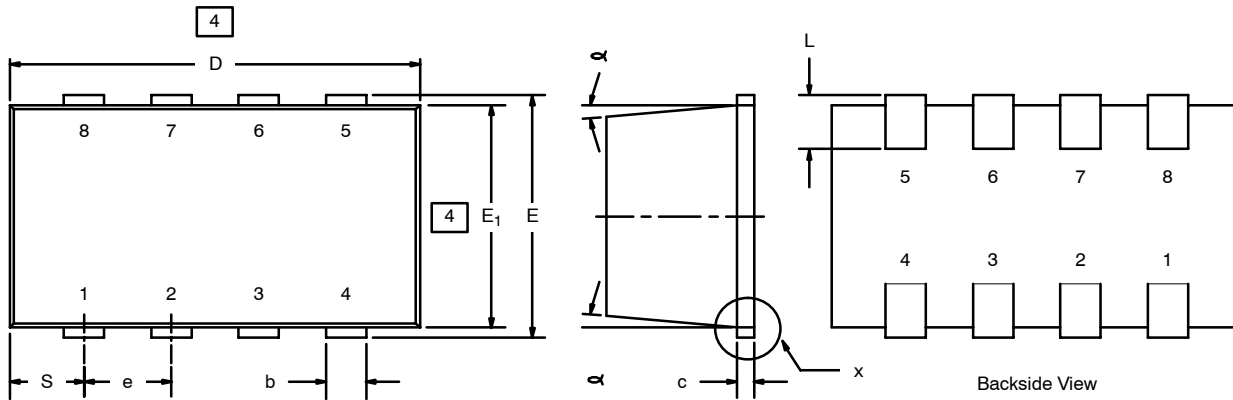


### 1206-8 ChipFET®



DETAIL X

**NOTES:**

1. All dimensions are in millimeters.
2. Mold gate burrs shall not exceed 0.13 mm per side.
3. Leadframe to molded body offset is horizontal and vertical shall not exceed 0.08 mm.

**4.** Dimensions exclusive of mold gate burrs.

5. No mold flash allowed on the top and bottom lead surface.

Dim	MILLIMETERS			INCHES		
	Min	Nom	Max	Min	Nom	Max
<b>A</b>	1.00	—	1.10	0.039	—	0.043
<b>b</b>	0.25	0.30	0.35	0.010	0.012	0.014
<b>c</b>	0.1	0.15	0.20	0.004	0.006	0.008
<b>c1</b>	0	—	0.038	0	—	0.0015
<b>D</b>	2.95	3.05	3.10	0.116	0.120	0.122
<b>E</b>	1.825	1.90	1.975	0.072	0.075	0.078
<b>E<sub>1</sub></b>	1.55	1.65	1.70	0.061	0.065	0.067
<b>e</b>	0.65 BSC			0.0256 BSC		
<b>L</b>	0.28	—	0.42	0.011	—	0.017
<b>S</b>	0.55 BSC			0.022 BSC		
<b>α</b>	5°Nom			5°Nom		
ECN: C-03528—Rev. F, 19-Jan-04 DWG: 5547						